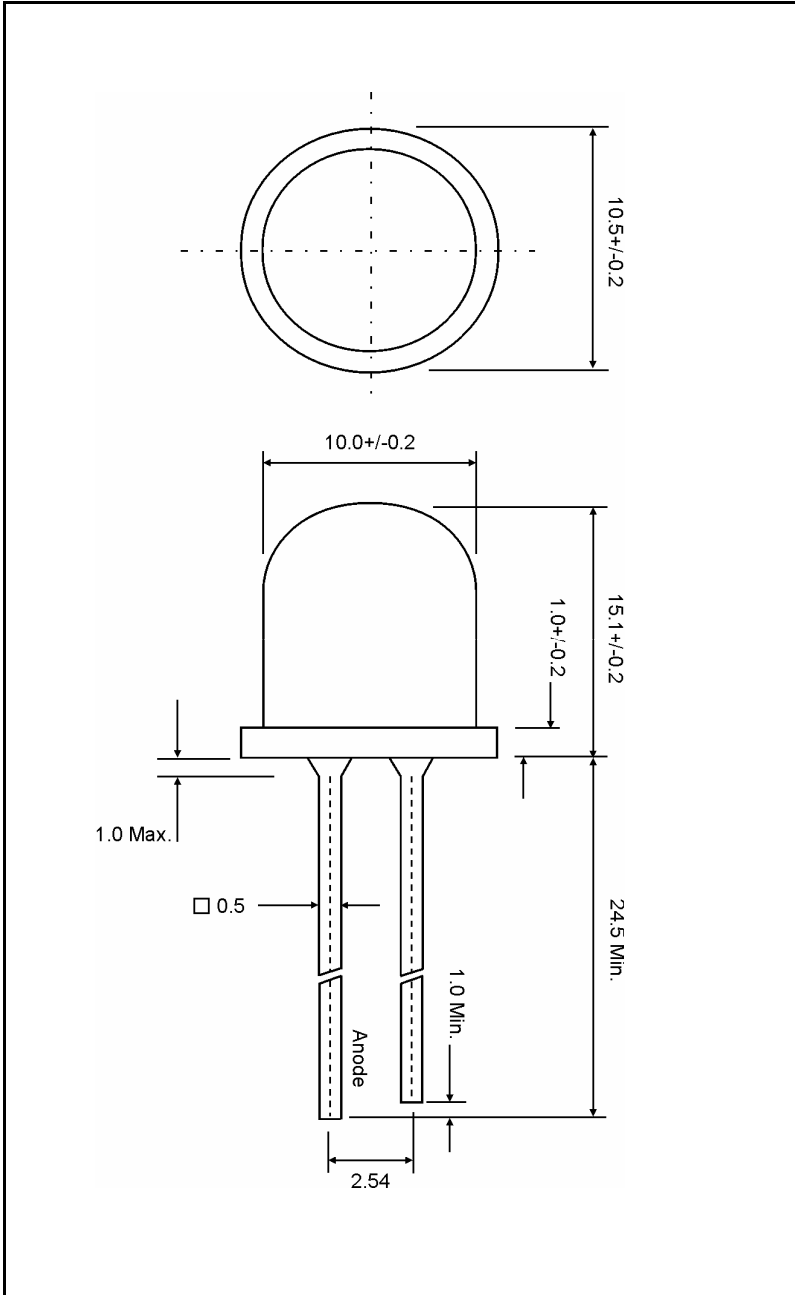


**Package Dimensions**



**Characters**

- 10mm Round
- Reliable and Rugged
- Low Power Consumption
- Low Working Current

**Functions**

- Power Indicator
- Back-Lighting
- Lighting Guide

**Notes**

1. All Dimensions are in millimeters
2. Tolerance is +/- 0.25mm unless otherwise noted
3. Protruded resin under flange is 1.0mm max.
4. Lead measured where the leads emerge from the package
5. ESD Class ( Mil-Std-883d Method 3015.7 ) based on

Human Body Mode : 1000V ( Ave. )

Chip Material	Emitting Color	Lens Color
GaN	Ultra Blue	Water Clear



**Electro-Optical Characteristics ( Ta=25°C )**

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Luminous Intensity	I <sub>v</sub>	4000		6000	mcd	I <sub>F</sub> = 20mA
Viewing Angle *	2θ <sup>1/2</sup>		20		Deg.	
Dominant Wavelength	λ <sub>d</sub>	465		470	nm	
Spectrum Radiation Bandwidth	Δλ		21		nm	
Forward Voltage	V <sub>F</sub>	3.0	3.3	3.6	V	
Recommended Working Current	R <sub>IF</sub>	10	20	25	mA	

\* Viewing Angle is defined as the off-axis angle where the Luminous Intensity is 1/2 the peak intensity.

**Absolute Maximum Ratings ( Ta=25°C )**

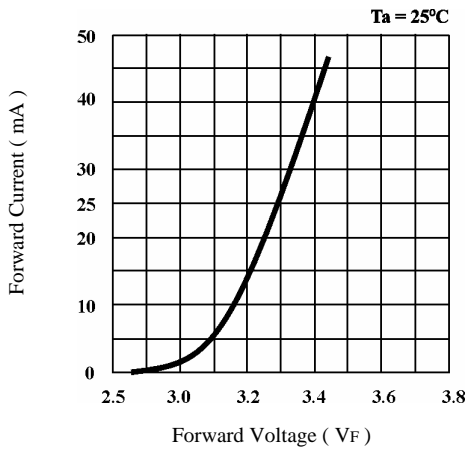
Parameter	Symbol	Max.	Unit
Power Dissipation	P <sub>D</sub>	100	mW
DC Forward Current	I <sub>F</sub>	30	mA
Peak Forward Current #	I <sub>PF</sub>	120	mA
Reverse Voltage	V <sub>R</sub>	5	V
Reverse Current	I <sub>R</sub>	10	uA
Operation Temperature Range	T <sub>opr</sub>	+ 80 ~ - 30	Deg.
Storage Temperature Range	T <sub>stg</sub>	+ 100 ~ - 40	Deg.
Soldering Temperature Range *	T <sub>sol</sub>	260°C for 5 Seconds	Deg.

# Duty Ratio = 1/16 , Pulse width = 0.1ms

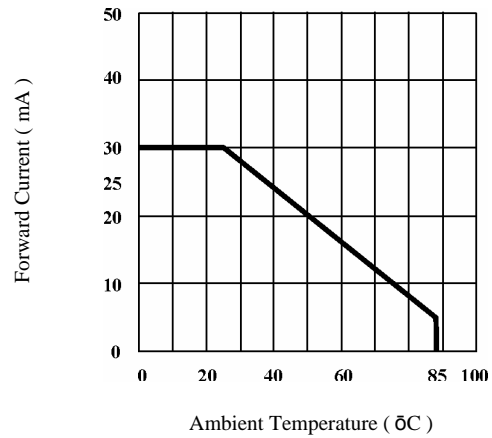
\* Lead Soldering Temperature Range ( 1.6mm from LED Body )

**Typical Electro-Optical Characteristics Curves**

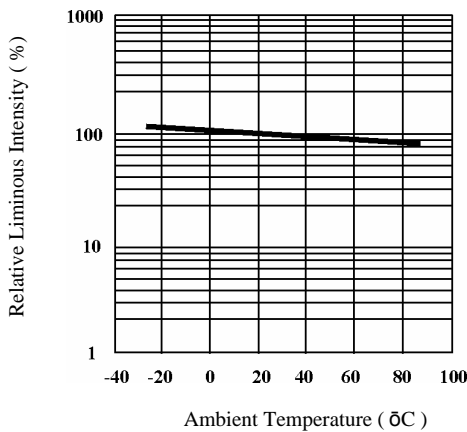
Forward Current VS Forward Voltage



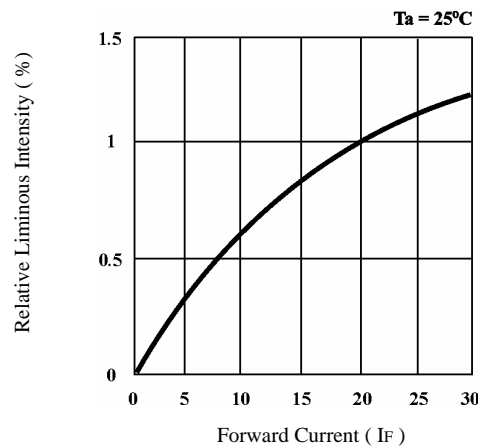
Forward Current VS Ambient Temperature



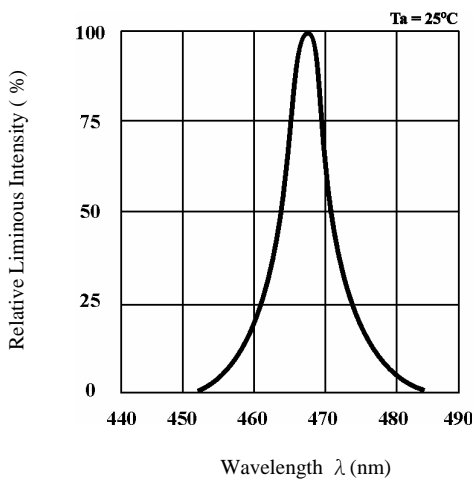
Luminous Intensity VS Ambient Temperature



Luminous Intensity VS Forward Current



Spectrum Distribution



Viewing Angle Diagram

